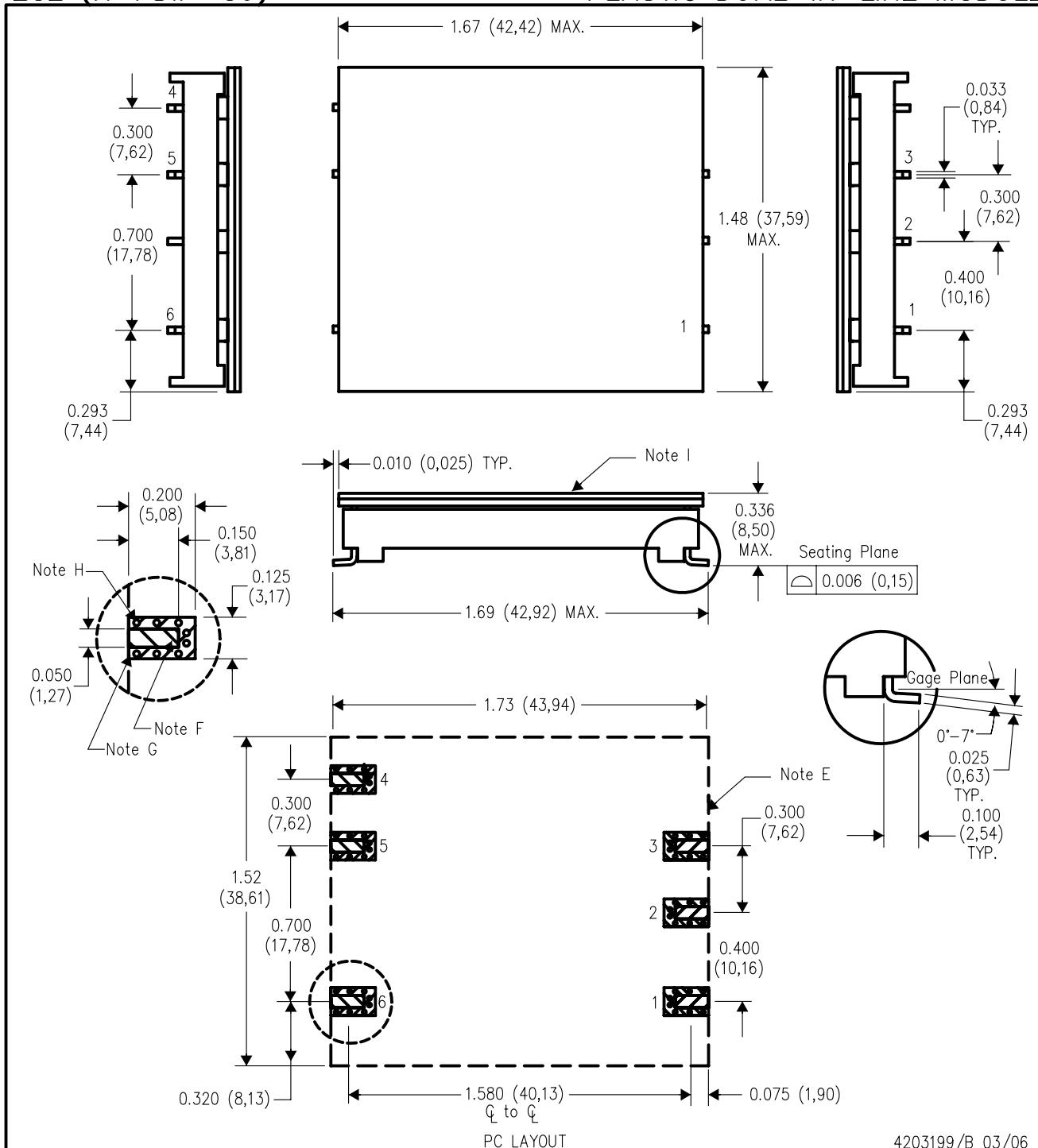


EGE (R-PDIP-G6)

PLASTIC DUAL-IN-LINE MODULE



NOTES:

- A. All linear dimensions are in inches (mm).
- B. This drawing is subject to change without notice.
- C. 2 place decimals are ± 0.030 ($\pm 0.76\text{mm}$).
- D. 3 place decimals are ± 0.010 ($\pm 0.25\text{mm}$).
- E. Recommended mechanical keep out area.
- F. Solder mask openings to copper island for solder joints to mechanical pins.

- G. Power pin connections should utilize two or more vias per input, ground and output pin.
- H. Vias are recommended to improve copper adhesion.
- I. The case is electrically isolated.

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